NOTE 1. CONTACT PLATING
CONTACT AREA: GOLD 0.1 μm MIN. OVER PALLADIUM/NICKEL 0.5 μm
TERMINAL AREA: GOLD 0.05 μm
ALL OVER NICKEL UNDERPLATED

2. APPLICABLE CABLE COVER: P/N: HDRE-E100LPA ( ) AND OTHERS
3. MATING CONNECTOR: P/N: HDRE-E100W ( ) LFDT1EC-SL+ AND OTHERS
4. APPLICABLE WIRE SIZE: AWG#30 (7/0.1)
Ø0.58 (INSULATION O.D.)